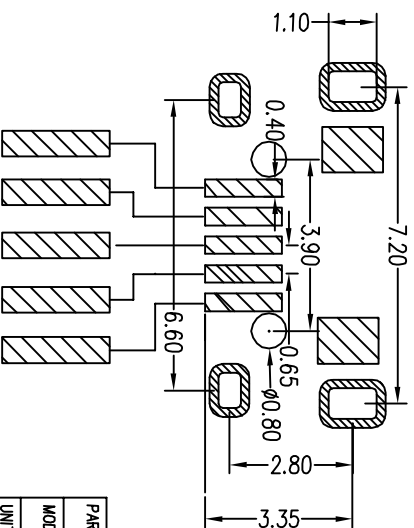
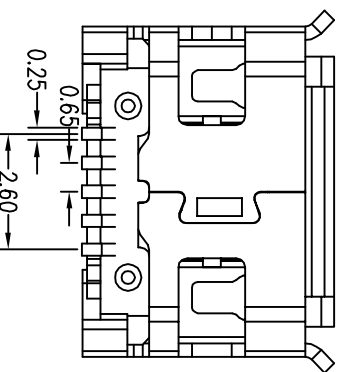
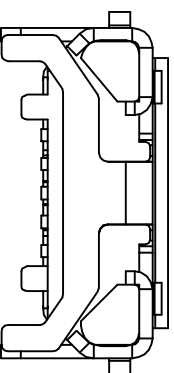
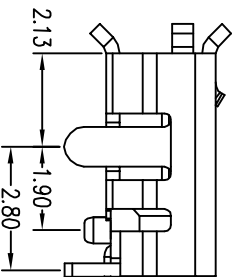
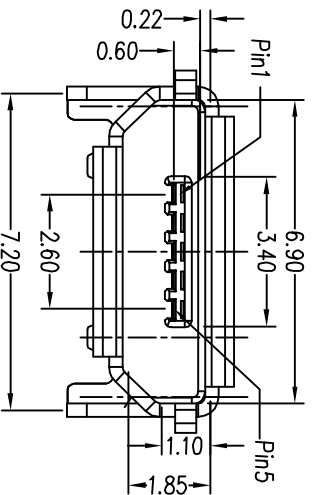
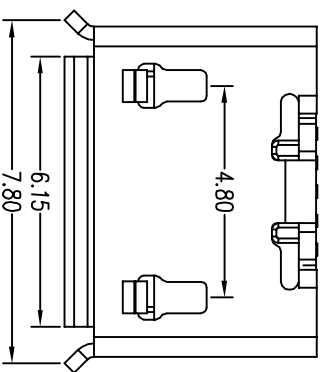


REV.	EQN NO	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



**Notes:**

**1. Materials:**

- 1.1 Housing: High temperature thermoplastic with g.f. UL94 V-0.
- 1.2 Contact: copper alloy, t=0.15mm.
- 1.3 Shell: copper alloy, t=0.30mm.

**2. Specifications:**

- 2.1. Current rating: 1 A Max.
- 2.2. Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3. Contact resistance: 50 mW Max.
- 2.4. Insulation resistance: 100 MW Min.
- 2.5. Total mating force: 3.57 Kgf Max.
- 2.6. Total unmating force: 1.0 Kgf Min. 0.81~2.05 Kgf Min. after 10000 Insertion/extraction cycles
- 2.7. Temperature range: -30°C~+80°C

PART NO: 98-MB05PMXX-01		MATERIAL:	
MODEL NO: FD098	FINSH:	TITLE: MIRCOC USB 5S B TYPE牛角型 D I P6.6/7.2	
UNIT: MM	SIZE: A4		
TOLERANCE UNSPECIFIED			
.x ±0.25	DR:		
.xx ±0.10	CHK:	DWG NO:	REV: A
.xxx ±0.05	APP:	SCALE: 1:1	SHEET: 2008/12/18
ANG. ±1°			

F 1 2 3 4 5 6 7 8

E 1 2 3 4 5 6 7 8

D 1 2 3 4 5 6 7 8

C 1 2 3 4 5 6 7 8

B 1 2 3 4 5 6 7 8

A 1 2 3 4 5 6 7 8